

ABSTRACT OF THE DISCLOSURE

A semiconductor fabrication system, method and medium are disclosed. The system includes a semiconductor fabrication tool and a software application, in communication with the semiconductor fabrication tool. The semiconductor fabrication tool includes a chamber
5 configured to perform at least one process on a semiconductor wafer. The software application is configured to determine specified qualities of the first chamber in performing the at least one process. The specified qualities are directed to at least one of: a processing time required to perform the at least one process, a rate of producing defective output products of the at least one
process, a uniformity of output products of the at least one process, and a capability index of the
10 at least one process.

09527444-001301